

cases	doc_1		doc_2		decision	id
			authors	<ul style="list-style-type: none">Ruiyang LiEungkyu LeeTengfei Luo	DUPLICATES	206
			title	Physics-Informed Neural Networks for Solving Multiscale Mode-Resolved Phonon Boltzmann Transport Equation		
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	authors	<ul style="list-style-type: none">Li, R.Lee, E.Luo, T.	source	SupportedSources.ARXIV		
	title	Physics-informed neural networks for solving multiscale mode-resolved phonon Boltzmann transport equation	journal	None		
	publication_date	2021-01-01 00:00:00	volume			
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	journal		urls	<ul style="list-style-type: none">http://arxiv.org/pdf/2103.07983v2http://arxiv.org/abs/2103.07983v2http://arxiv.org/pdf/2103.07983v2		
	volume		id	id-4994003534815946117		
	doi	10.1016/j.mtphys.2021.100429	abstract	Boltzmann transport equation (BTE) is an ideal tool to describe the multiscale phonon transport phenomena, which are critical to applications like microelectronics cooling. Numerically solving phonon BTE is extremely computationally challenging due to the high dimensionality of such problems, especially when mode-resolved properties are considered. In this work, we demonstrate the use of physics-informed neural networks (PINNs) to efficiently solve phonon BTE for multiscale thermal transport problems with the consideration of phonon dispersion and polarization. In particular, a PINN framework is devised to predict the phonon energy distribution by minimizing the residuals of governing equations and boundary conditions, without the need for any labeled training data. Moreover, geometric parameters, such as the characteristic length scale, are included as a part of the input to PINN, which enables learning BTE solutions in a parametric setting. The effectiveness of the present scheme is demonstrated by solving a number of phonon transport problems in different spatial dimensions (from 1D to 3D). Compared to existing numerical BTE solvers, the proposed method exhibits superiority in efficiency and accuracy, showing great promises for practical applications, such as the thermal design of electronic devices.		
	urls	<ul style="list-style-type: none">https://api.elsevier.com/content/article/PII:S2542529321000900?httpAccept=text/xmlhttps://api.elsevier.com/content/article/PII:S2542529321000900?httpAccept=text/plainhttp://dx.doi.org/10.1016/j.mtphys.2021.100429	versions			
	id	id-2696274804019518240				
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